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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE


Applicant : Matsumura, et al.
Appl. No. : 10/678,855
Filed : October 3, 2003
For : DICING/DIE-BONDING FILM,
METHOD OF FIXING CHIPPED
WORK AND SEMICONDUCTOR
DEVICE
Examiner : Laura M Schillinger
Group Art Unit : 2813

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

March 24, 2005

(Date)


Katsuhiro Arai, Reg. No. 43,315

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed December 28, 2004, please reconsider the present application in light of the following amendments and comments.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.